

### **ABSTRACT OF THE DISCLOSURE**

A compact electronic device includes at least a substrate, one semiconductor chip, one passive component, and a molding compound. A plurality of conductive traces are formed on a first surface of the substrate. A plurality of terminals are peripherally formed on a second surface of the substrate and externally exposed as the input/output connections of the compact electronic device. The conductive traces on the first surface are electrically connected to the terminals on the second surface by a plurality of vias. The semiconductor chip and the passive component are mounted on the first surface of the substrate and electrically connected to the substrate through a plurality of connectors. The molding compound covers the first surface of the substrate to encapsulate both the semiconductor chip and the passive components electrically connected to the substrate.